



N 沟道增强型场效应晶体管 N-CHANNEL MOSFET FHA50N50W

主要参数 MAIN CHARACTERISTICS

ID	50A
VDSS	500V
Rdson-typ (@Vgs=10V)	88 mΩ
Qg-typ	148 nC

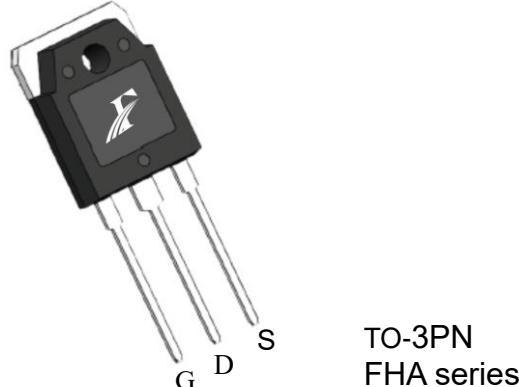
用途 APPLICATIONS

高频开关电源	High efficiency switch mode power supplies
逆变电源	Power management for inverter systems

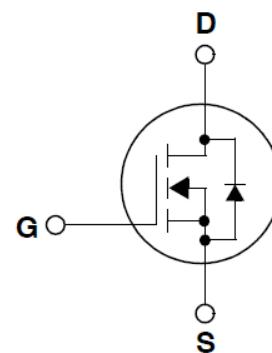
产品特性 FEATURES

低栅极电荷	Low gate charge
低 Crss (典型值 34 pF)	Low Crss (typical 34 pF)
开关速度快	Fast switching
100% 经过雪崩测试	100% avalanche tested
100% 经过热阻测试	100% DVDS tested
100% 经过 RG 测试	100% Rg tested
高抗 dv/dt 能力	Improved dv/dt capability
RoHS 产品	RoHS product

封装形式 Package



等效电路 Equivalent Circuit



绝对最大额定值 ABSOLUTE RATINGS (Tc=25°C)

项目 Parameter	符号 Symbol	数值 Value	单位 Unit
		FHA50N50W	
最高漏极—源极直流电压 Drain-Source Voltage	VDS	500	V
连续漏极电流* Drain Current -continuous *	I _D (Tc=25°C)	50	A
	I _D (Tc=100°C)	31	A
最大脉冲漏极电流 (注 1) Drain Current – pulse (note 1)	I _{DM}	200	A
最高栅源电压 Gate-Source Voltage	V _{GS}	±30	V
单脉冲雪崩能量 (注 2) Single Pulsed Avalanche Energy (note 2)	E _{AS}	3380	mJ
雪崩电流 (注 1) Avalanche Current (note 1)	I _{AR}	26	A
重复雪崩能量 (注 1) Repetitive Avalanche Current (note 1)	E _{AR}	140	mJ
二极管反向恢复最大电压变化速率 (注 3) Peak Diode Recovery dv/dt (note 3)	dv/dt	5.0	V/ns
耗散功率 Power Dissipation	P _D (TC=25°C)	500	W
	-Derate above 25°C	4	W/°C
最高结温及存储温度 Operating and Storage Temperature Range	T _J , T _{STG}	150, -55 to 150	°C
引线最高焊接温度 Maximum Lead Temperature for Soldering Purposes	T _L	300	°C

*漏极电流由最高结温限制

*Drain current limited by maximum junction temperature

电特性 ELECTRICAL CHARACTERISTICS

项目 Parameter	符号 Symbol	测试条件 Tests conditions	最小 Min	典型 Typ	最大 Max	单位 Units	
关态特性 Off -Characteristics							
漏一源击穿电压 Drain-Source Voltage	BV_{DSS}	$I_D=250\mu A, V_{GS}=0V$	500	-	-	V	
击穿电压温度特性 Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	$I_D=250\mu A$, referenced to $25^\circ C$	-	0.5	-	V/ $^\circ C$	
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=500V, V_{GS}=0V, T_c=25^\circ C$	-	-	10	μA	
		$V_{DS}=400V, T_c=125^\circ C$	-	-	100	μA	
栅极体漏电流 Gate-body leakage current	$I_{GSS} (F/R)$	$V_{DS}=0V, V_{GS}=\pm 30V$	-	-	± 100	nA	
通态特性 On-Characteristics							
阈值电压 Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D=250\mu A$	2.0	-	4.0	V	
静态导通电阻 Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D=25A$	-	88	105	$m\Omega$	
正向跨导 Forward Transconductance	g_{fs}	$V_{DS} = 20V, I_D=25A$ (note 4)	-	20	-	S	
动态特性 Dynamic Characteristics							
栅电阻 Gate Resistance	R_g	$f=1.0MHz, V_{DS} OPEN$	-	0.9	-	Ω	
输入电容 Input capacitance	C_{iss}	$V_{DS}=25V,$ $V_{GS}=0V,$ $f=1.0MHz$	-	7950	-	pF	
输出电容 Output capacitance	C_{oss}		-	721	-		
反向传输电容 Reverse transfer capacitance	C_{rss}		-	34	-		
开关特性 Switching Characteristics							
延迟时间 Turn-On delay time	$t_{d(on)}$	$V_{DS}=250V,$ $I_D=50A,$ $R_g=20\Omega$ $V_{GS}=10V$ (note 4, 5)	-	60	-	ns	
上升时间 Turn-On rise time	t_r		-	130	-	ns	
延迟时间 Turn-Off delay time	$t_{d(off)}$		-	100	-	ns	
下降时间 Turn-Off Fall time	t_f		-	91	-	ns	
栅极电荷总量 Total Gate Charge	Q_g	$V_{DS}=400V,$ $I_D=50A,$ $V_{GS}=10V$ (note 4, 5)	-	148	-	nC	
栅一源电荷 Gate-Source charge	Q_{gs}		-	36	-	nC	
栅一漏电荷 Gate-Drain charge	Q_{gd}		-	94	-	nC	
漏一源二极管特性及最大额定值 Drain-Source Diode Characteristics and Maximum Ratings							
正向最大连续电流 Maximum Continuous Drain-Source Diode Forward Current	I_s		-	-	50	A	
正向最大脉冲电流 Maximum Pulsed Drain-Source Diode Forward Current	I_{SM}		-	-	200	A	
正向压降 Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=50A$	-	-	1.3	V	
反向恢复时间 Reverse recovery time	t_{rr}	$V_{GS}=0V, I_s=50A, dI/dt=100A/\mu s$ (note 4)	-	500	-	ns	
反向恢复电荷 Reverse recovery charge	Q_{rr}		-	8.32	-	μC	

热特性 THERMAL CHARACTERISTIC

项目 Parameter	符号 Symbol	FHA50N50W	单位 Unit
结到管壳的热阻 Thermal Resistance, Junction to Case	R _{th(j-c)}	0.25	°C/W
结到环境的热阻 Thermal Resistance, Junction to Ambient	R _{th(j-A)}	40	°C/W

注释:

- 1: 脉冲宽度由最高结温限制
- 2: L=10mH, IAS=26A, VDD=50V, RG=25 Ω, 起始结温 TJ=25°C
- 3: ISD ≤50A, di/dt ≤200A/μs, VDD≤BV_{DSS}, 起始结温 TJ=25°C
- 4: 脉冲测试: 脉冲宽度 ≤300μs, 占空比≤2%
- 5: 基本与工作温度无关

Notes:

- 1: Pulse width limited by maximum junction temperature
- 2: L=10mH, IAS=26A, VDD=50V, RG=25 Ω , Start TJ=25°C;
- 3: ISD ≤50A, di/dt ≤200A/μs, VDD≤BV_{DSS}, Starting TJ=25°C
- 4: Pulse Test: Pulse Width ≤300μs, Duty Cycle≤2%
- 5: Essentially independent of operating temperature

特性曲线 (ELECTRICAL CHARACTERISTICS (curves))

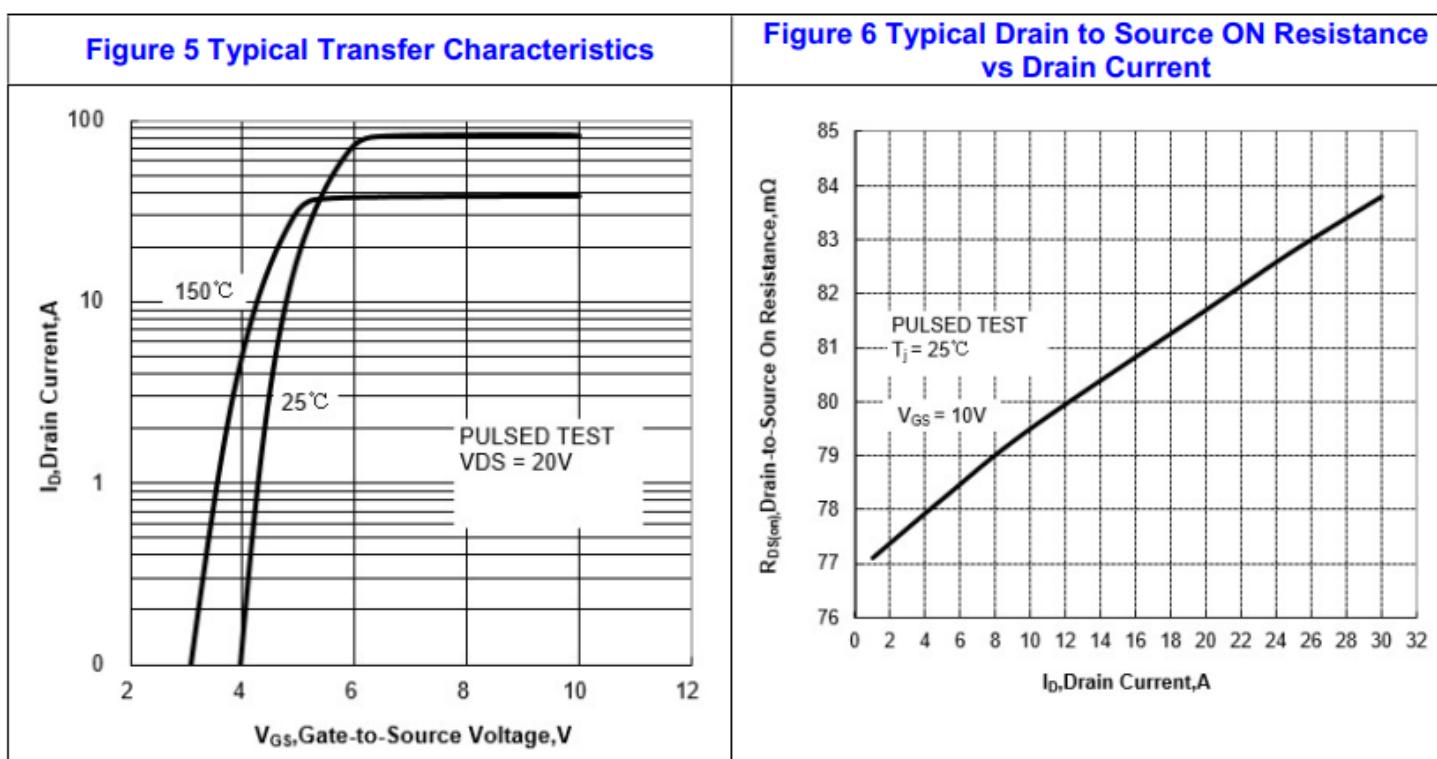
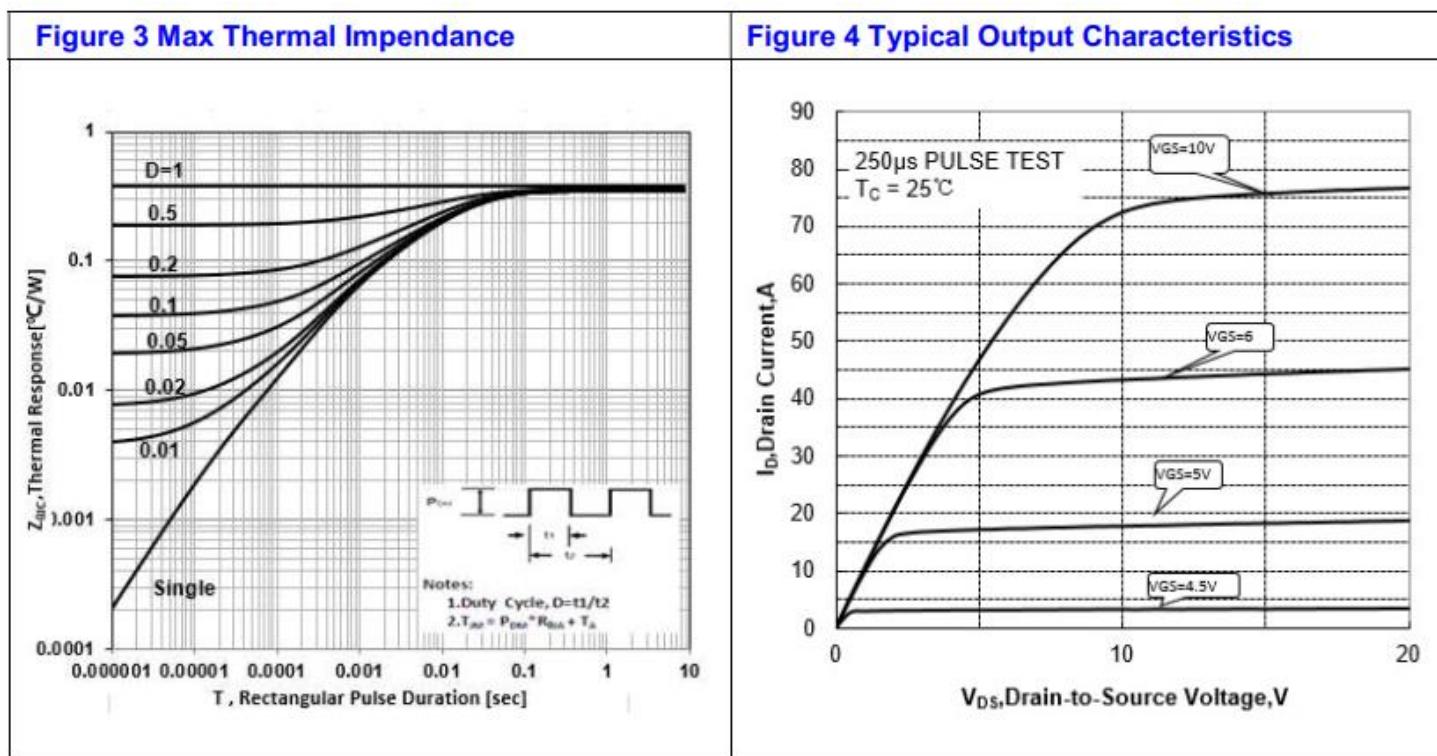
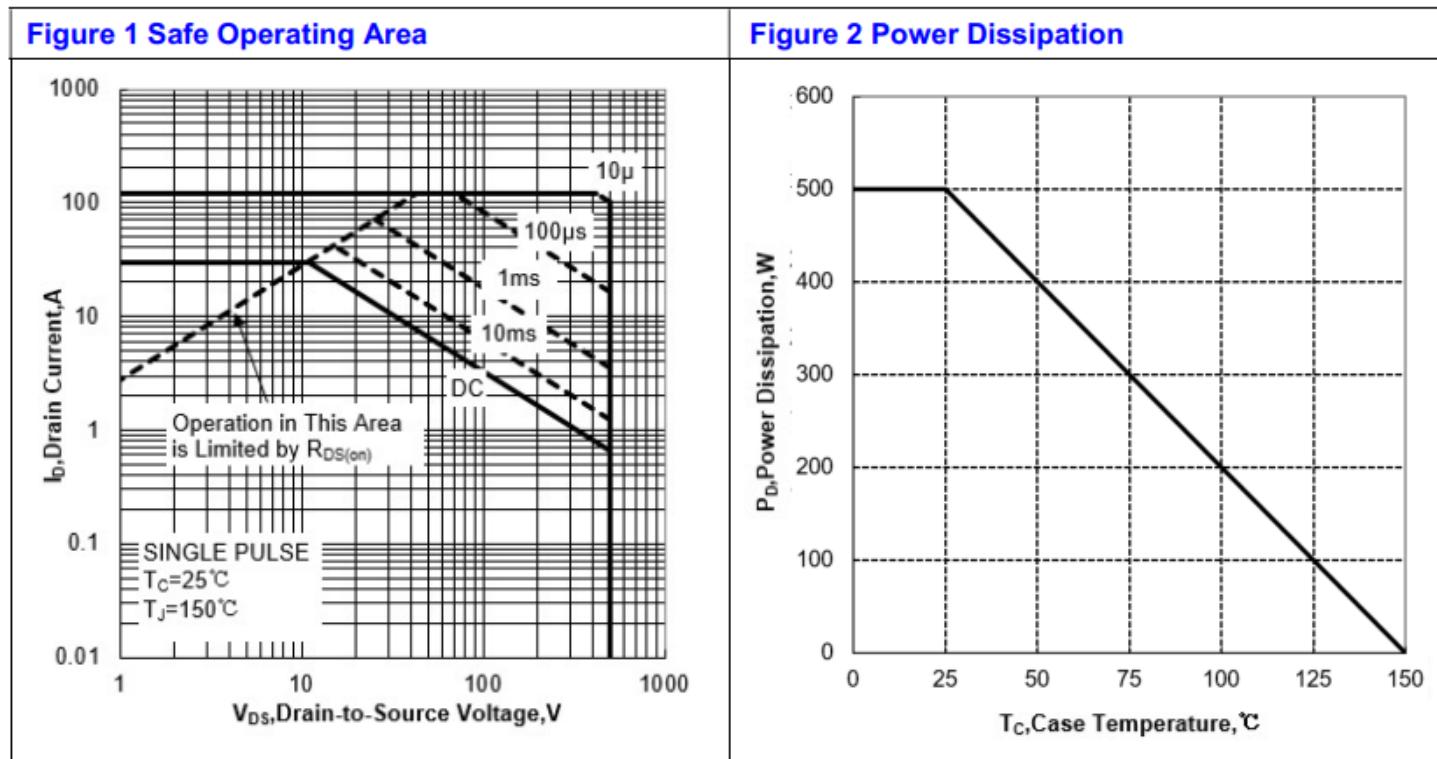


Figure 7 Typical Drian to Source on Resistance vs Junction Temperature

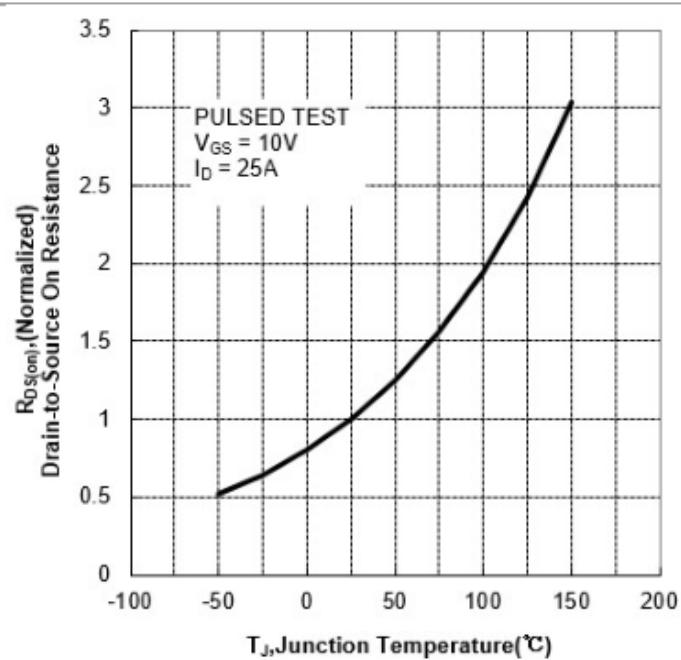


Figure 8 Typical Threshold Voltage vs Junction Temperature

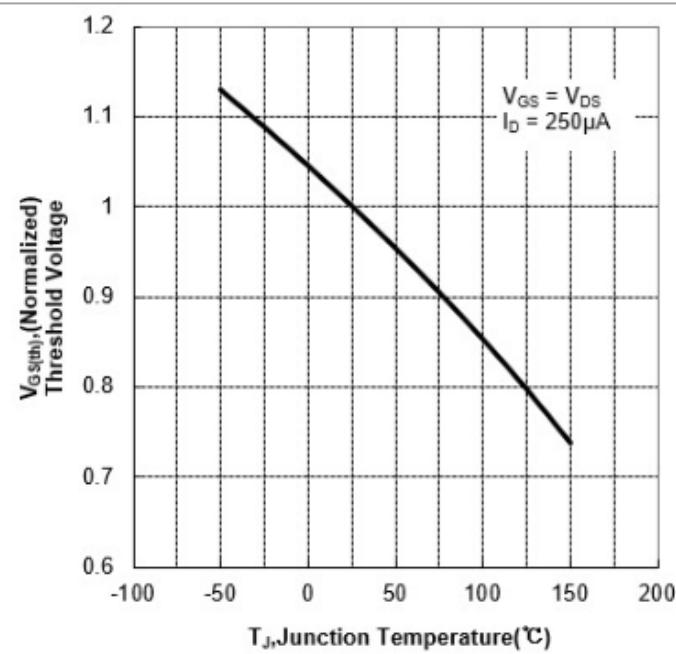


Figure 9 Typical Breakdown Voltage vs Junction Temperature

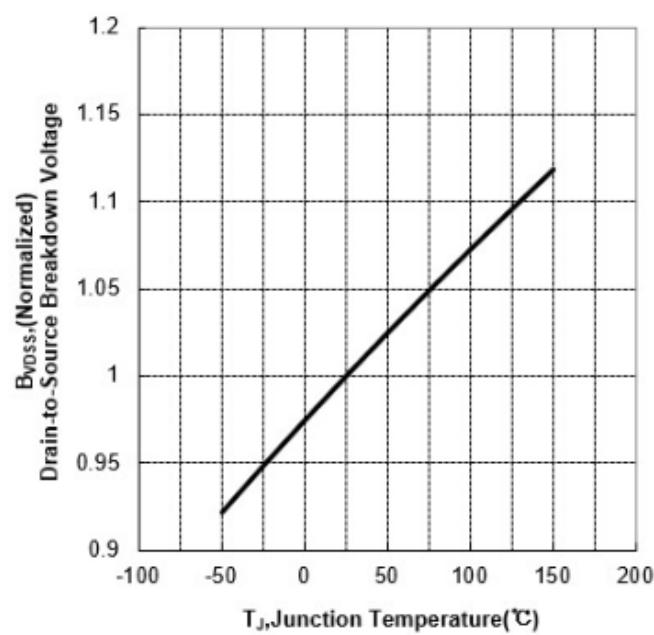


Figure 10 Typical Threshold Voltage vs Junction Temperature

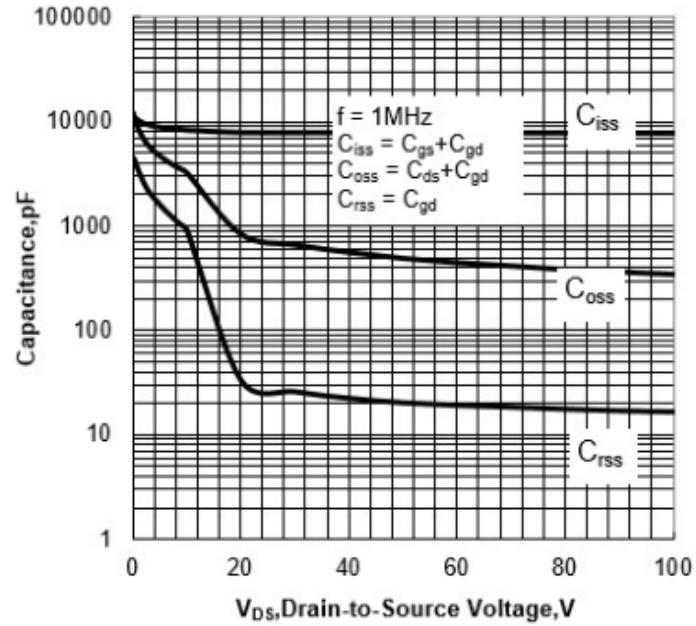
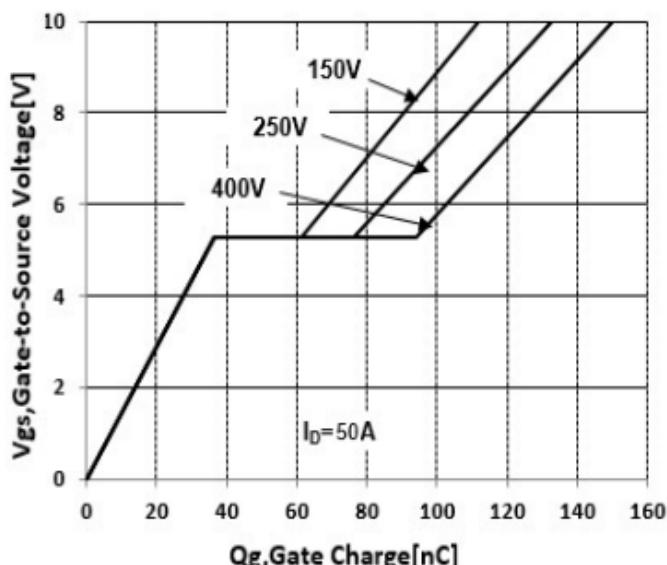


Figure 11 Typical Breakdown Voltage vs Junction Temperature



Test Circuit & Waveform

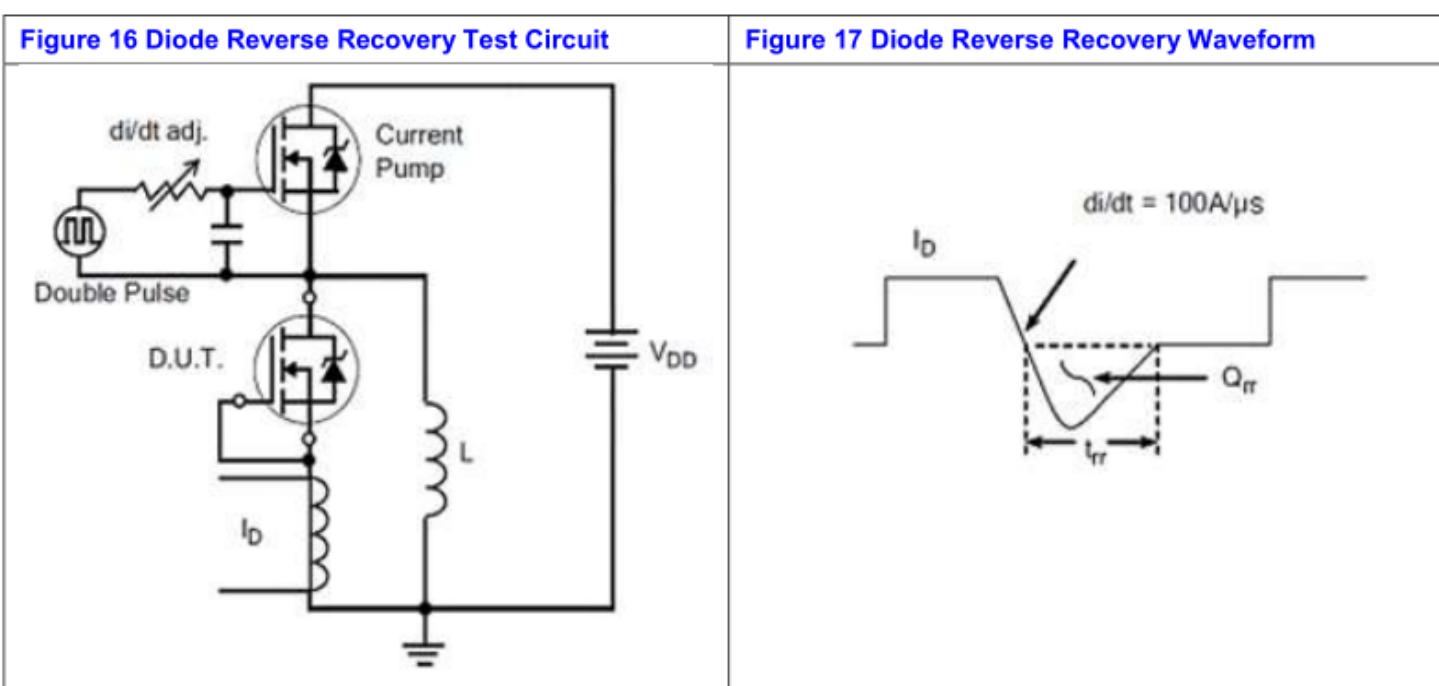
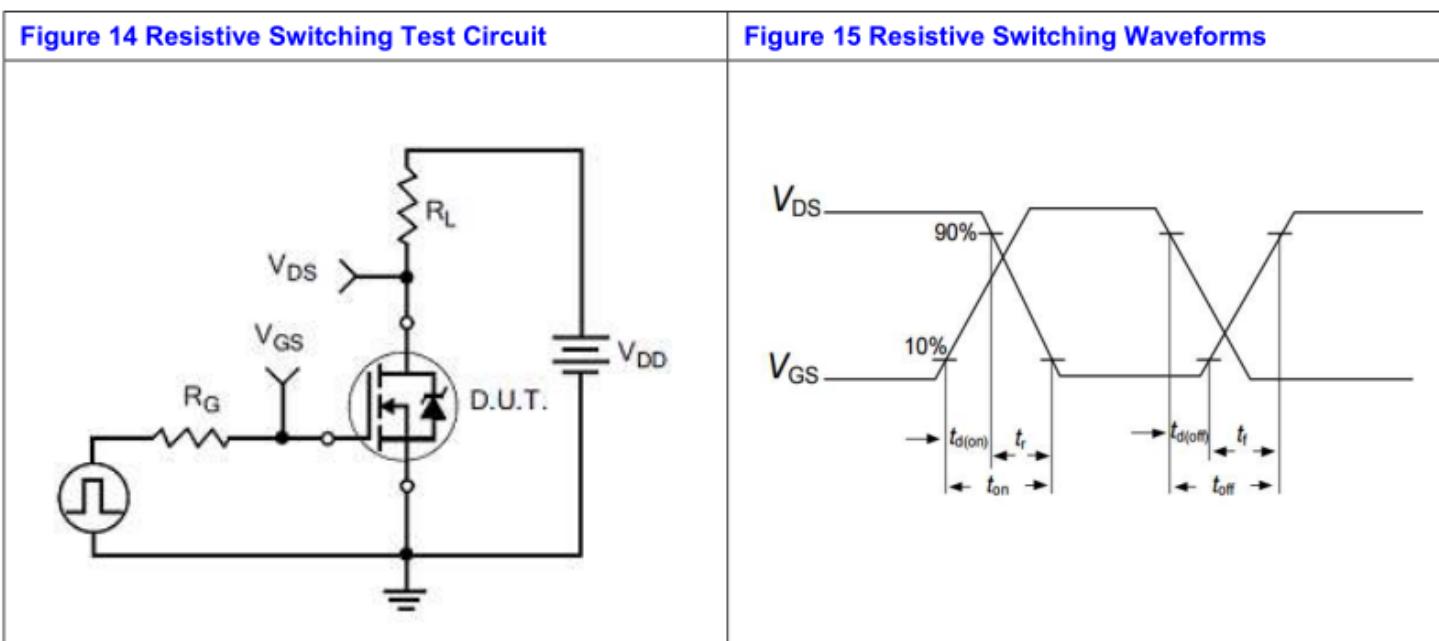
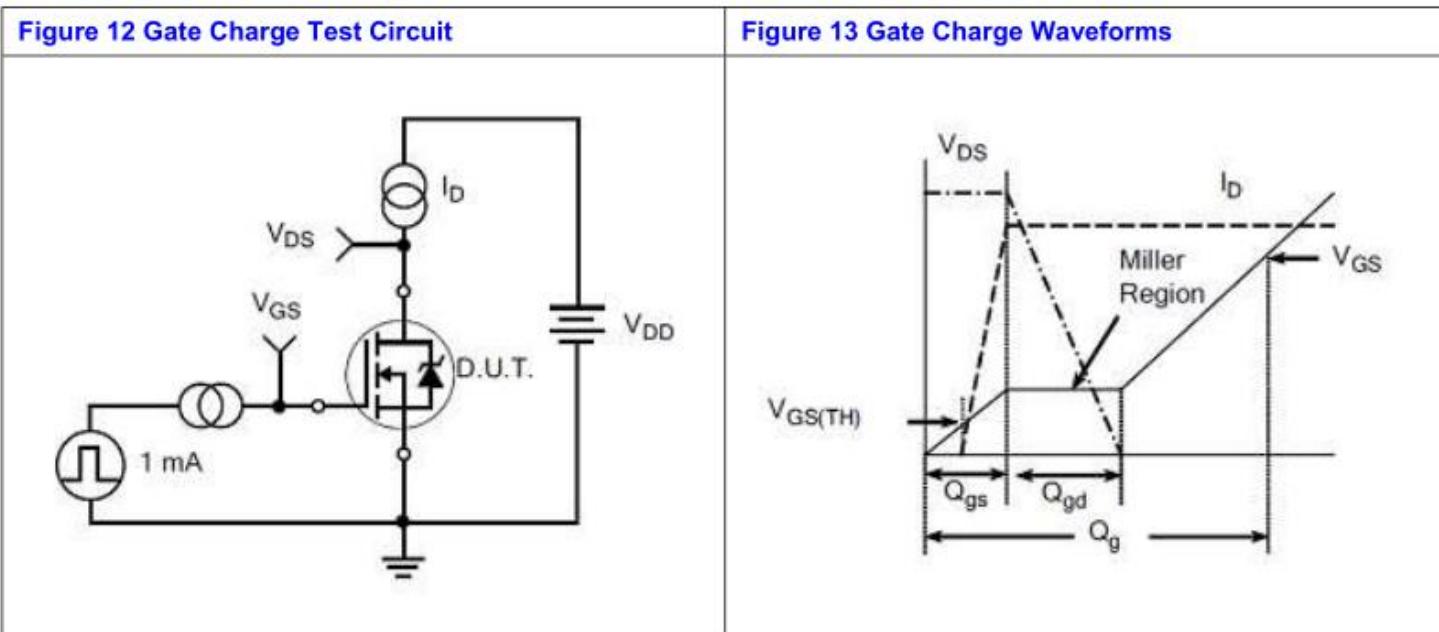


Figure 18 Unclamped Inductive Switching Test Circuit

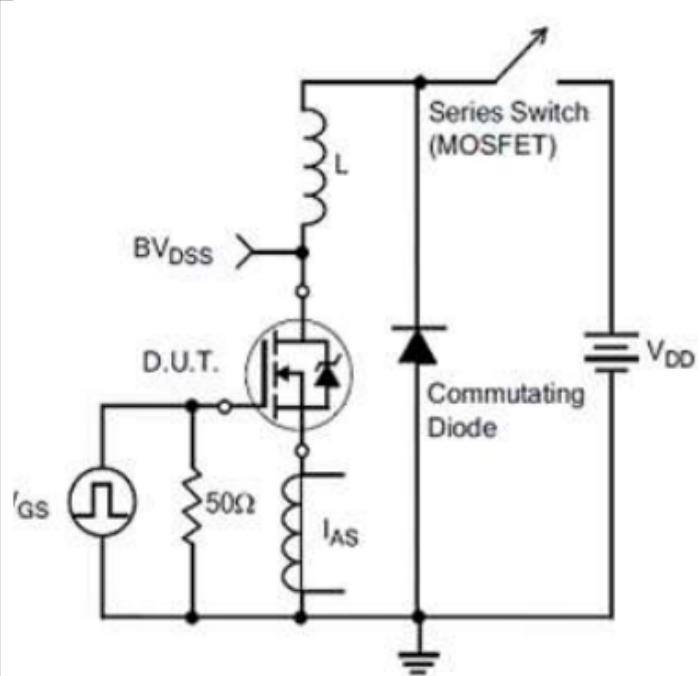
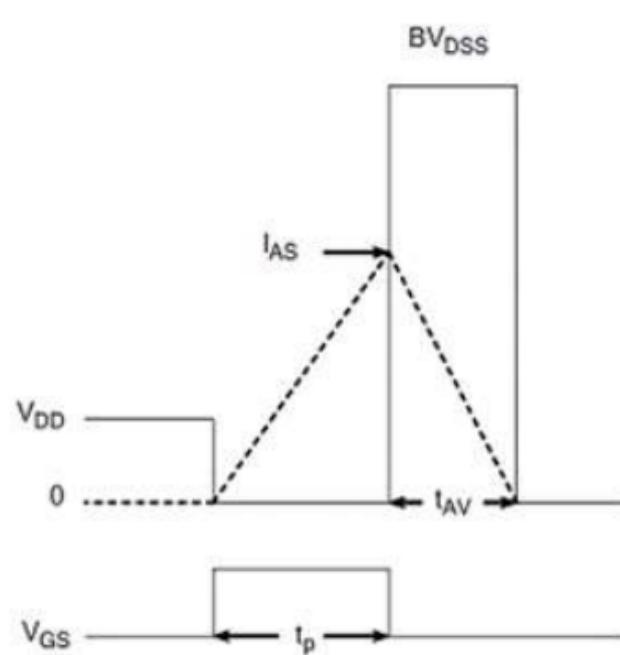
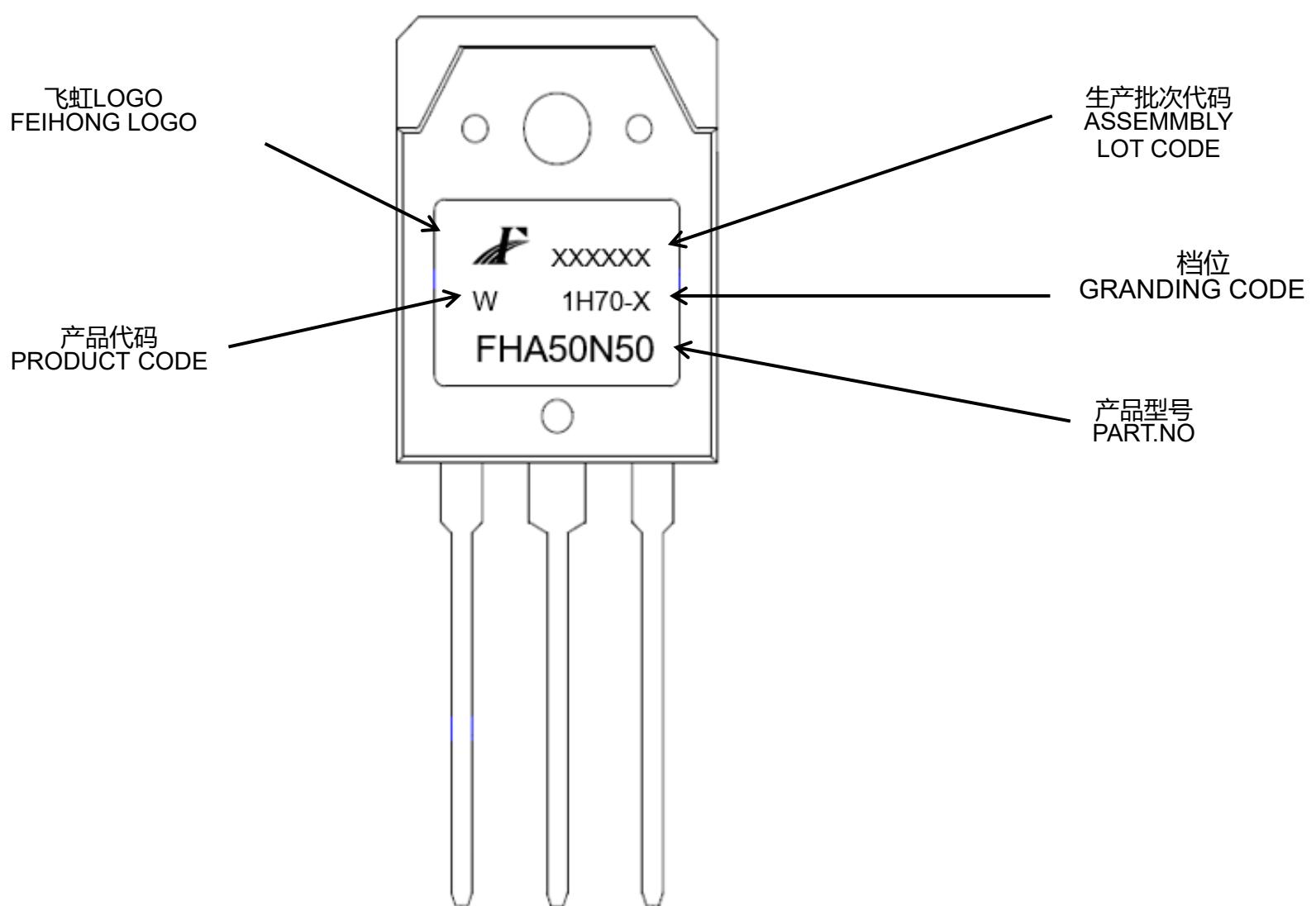


Figure 19 Unclamped Inductive Switching Waveform



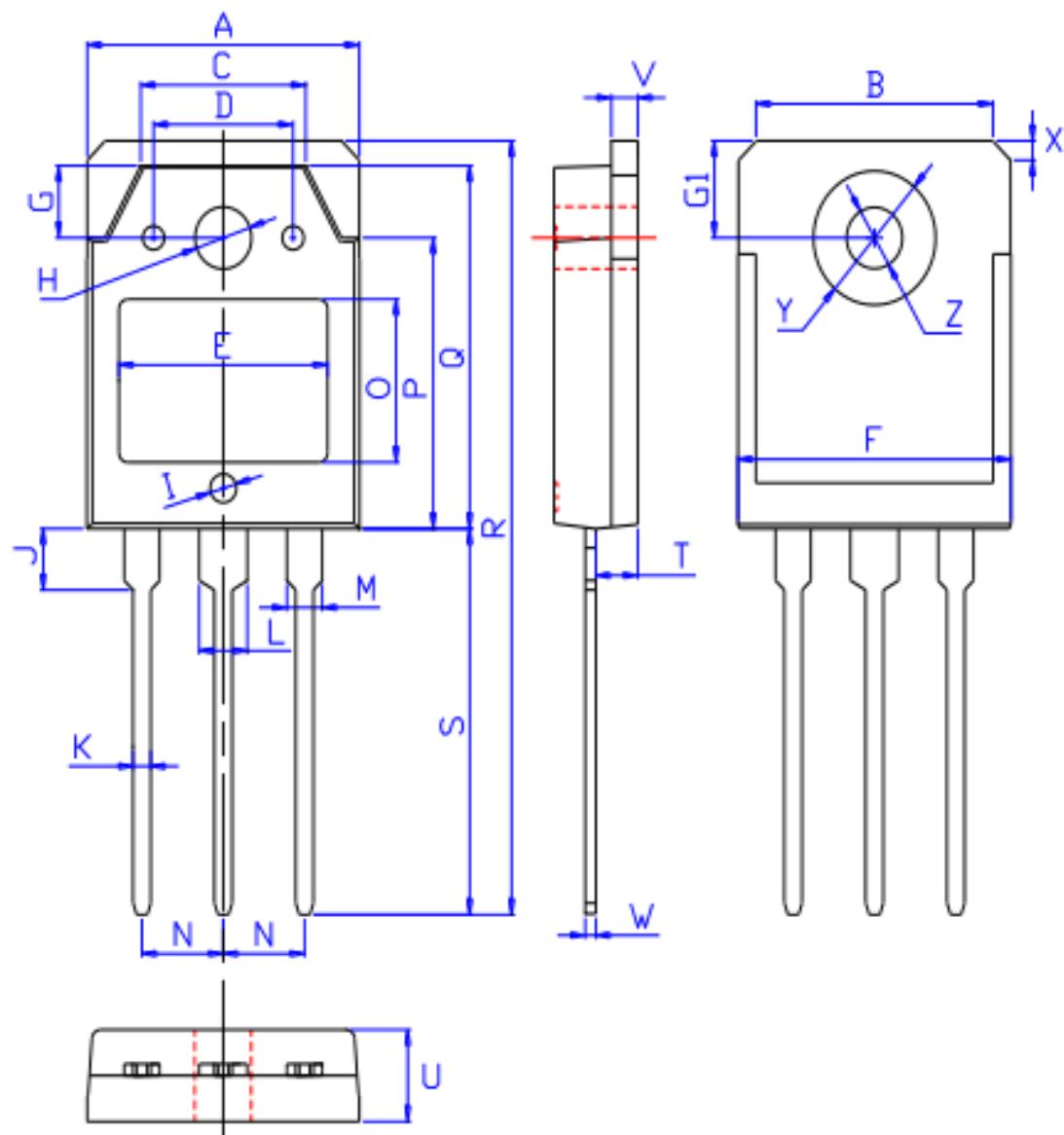
印记 Marking:



外形尺寸:

Package Dimension:

TO-3PN



DIM	MILLIMETERS
A	15.60±0.30
B	13.60±0.30
C	9.50±0.30
D	8.00±0.30
E	11.85±0.30
F	15.65±0.30
G	3.80±0.30
G1	5.00±0.30
H	Φ 3.50±0.30
I	Φ 1.50±0.30 深 0.15±0.15
J	3.20±0.30
K	1.00±0.15
L	3.10±0.15
M	2.10±0.15
N	5.45±0.30
O	8.40±0.30
P	13.90±0.30
Q	18.70±0.30
R	40.00±0.60
S	20.00±0.40
T	2.40±0.30
U	4.80±0.30
V	1.50±0.15
W	0.60±0.15
X	1.80±0.40
Y	7.00±0.30
Z	3.20±0.30

(Units: mm)